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Claims

What is claimed is:

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1. A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate;

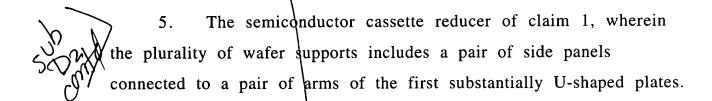
a second substantially U-shaped plate;

a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate; and more than two retention springs attached to the first substantially U-shaped plate.

2. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a pair of interior arm cutouts.

3. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a base cutout.

4. The semiconductor cassette reducer of claim 1, wherein a base to tip distance is less than an interior depth of a front opening unified pod.



- 6. The semiconductor cassette reducer of claim 5, wherein the pair of side panels have a plurality of lips.
- 7. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has an exterior partial S-shaped cutout.
- 8. The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of columns.
- 9. The semiconductor cassette reducer of claim 9, wherein the pair of columns have at least two positions.
 - 10. A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate having a first pair of arms each having a first arm cutout;

a second substantially U-shaped plate having a second pair of arms each having a second arm cutout;

a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate.

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11. The semiconductor cassette reducer of claim 10, further including a plurality of retention springs attached to the first substantially U-shaped plate.

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12. The semiconductor cassette reducer of claim 11, wherein one of the plurality of retention springs is designed to mate with a lip of a front opening unified pod.

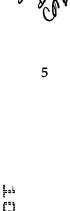
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13. The semiconductor cassette reducer of claim 10, wherein the plurality of wafer supports include a wafer support panel attached to one of the first pair of arms.

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- 14. A semiconductor cassette reducer comprising:
- a first substantially U-shaped plate;
- a second substantially U-shaped plate;
- a first wafer support panel attached to a first arm of the first substantially U-shaped plate and to a first arm of the second substantially U-shaped plate; and
- a second wafer support panel attached to a second arm of the first substantially U-shaped plate and to a second arm of the second substantially U-shaped plate.

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15. The semiconductor cassette reducer of claim 14, further including a pair of column wafer supports attached to a base of the first substantially U-shaped plate and to a base of the second substantially U-shaped plate.

16. The semiconductor cassette reducer of claim 14, wherein the first substantially U shaped plate has a plurality of flexible disks.

17. The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a pair of arms each having an interior cutout.

18. The semiconductor cassette reducer of claim 14, wherein a base to tip distance is less than a diameter of wafer designed for a front opening unified pod.